

Innovating Energy Technology

http://www.fujielectric.com/products/semiconductor/ **FUJI POWER MOSFET**

Super J MOS[®] S1 series

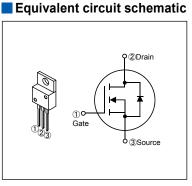
N-Channel enhancement mode power MOSFET

Features

Pb-free lead terminal **RoHS** compliant

Applications For switching

Outline Drawings [mm] TO-220 \oplus . .



Absolute Maximum Ratings at Tc=25°C (unless otherwise specified)

Parameter	Symbol	Characteristics	Unit	Remarks
Drain Source Voltage	VDS	600	V	
Drain-Source Voltage	VDSX	600	V	V _{GS} =-30V
Continuous Drain Current	lo Rote	10 ±30	A	Tc=25°C Note*1
		日月二十月日日	A	Tc=100°C Note*1
Pulsed Drain Current	IDP 9	\$158 ±90 4 P	A	Note*1
Gate-Source Voltage	Ves	5 × 1±30	V	
Repetitive and Non-Repetitive Maximum Avalanche Current	TAR	diffet	А	Note *2
Non-Repetitive Maximum Avalanche Energy	The PI	849.2 5	す∘ mJ	Note *3
Maximum Drain-Source dV/dt	dV₀s/dt	5願し、50	kV/µs	V _{DS} ≤ 600V
Peak Diode Recovery dV/dt	dV/dt/J	igning80	kV/μs	Note *4
Peak Diode Recovery -di/dt	di/dt new des	100	A/µs	Note *5
Maximum Power Dissipation 新規設計になった		2.02	w	T _a =25°C
Maximum Power Dissipation Derating and Storage Temperature Pange		250	vv	T₀=25°C
Operating and Storage Temperatury Ofte	Tch	150	°C	
Operating and Storage Temperature range	T _{stg}	-55 to +150	°C	

Note *1 : Limited by maximum channel temperature. Note *2 : Tch≤150°C, See Fig.1 and Fig.2 Note *3 : Starting Tch=25°C, I₄s=4A, L=97.3mH, Vpp=60V, Rg=50Ω, See Fig.1 and Fig.2

EAs limited by maximum channel temperature and avalanche current. Note *4 : Ir≤-ID, -di/dt=100A/µs, VDs peak≤600V, Tch≤150°C.

Note *5 : IF≤-ID, dV/dt=30kV/µs, VDS peak≤600V, Tch≤150°C.

Electrical Characteristics at T_c=25°C (unless otherwise specified) Static Ratings

Parameter	Symbol	Conditions		min.	typ.	max.	Unit
Drain-Source Breakdown Voltage	BV _{DSS}	I _D =250μA V _{GS} =0V		600	-	-	V
Gate Threshold Voltage	V _{GS(th)}	ID=1mA VDS=VGS		3	4	5	V
Zero Gate Voltage Drain Current		V _{DS} =600V V _{GS} =0V	T _{ch} =25°C	-	-	25	- μA
	IDSS	V _{DS} =480V V _{GS} =0V	T _{ch} =125°C	-	150	-	
Gate-Source Leakage Current	IGSS	V _{GS} = ± 30V V _{DS} =0V		-	10	100	nA
Drain-Source On-State Resistance	R _{DS(on)}	I _D =15A V _{GS} =10V		-	0.111	0.132	Ω
Gate resistance	Ro	f=1MHz, open drain		-	3.3	-	Ω

Dynamic Ratings

Parameter	Symbol	Conditions	min.	typ.	max.	Unit
Forward Transconductance	g _{fs}	I _D =15A V _{DS} =25V	11	23	-	S
Input Capacitance	Ciss	V _{DS} =400V	-	2080	-	
Output Capacitance	Coss	V _{GS} =0V	-	60	-	
Reverse Transfer Capacitance	Crss	f=250kHz	-	4	-	
Effective output capacitance, energy related (Note *6)	C _{o(er)}	V _{GS} =0V V _{DS} =0400V	-	160	-	pF
Effective output capacitance, time related (Note *7)	C _{o(tr)}	V _{GS} =0V V _{DS} =0400V ID=constant	-	535	-	
Turn-On Time	t _{d(on)}	V _{DD} =400V, V _{GS} =10V I _D =15A, R₀=27Ω See Fig.3 and Fig.4	-	119	-	
Turn-On Time	tr		-	32	-	
Turn-Off Time	td(off)		-	186	-	ns
	tr		-	22	-	
Total Gate Charge	Q _G	V _{DD} =400V, ID=30A	-	73	-	
Gate-Source Charge	Q _{GS}		-	22	-	
Gate-Drain Charge	QGD	⊣ V₀₅=10V _ See Fig.5	-	29	-	nC
Drain-Source crossover Charge	Qsw		-	11.5	-]

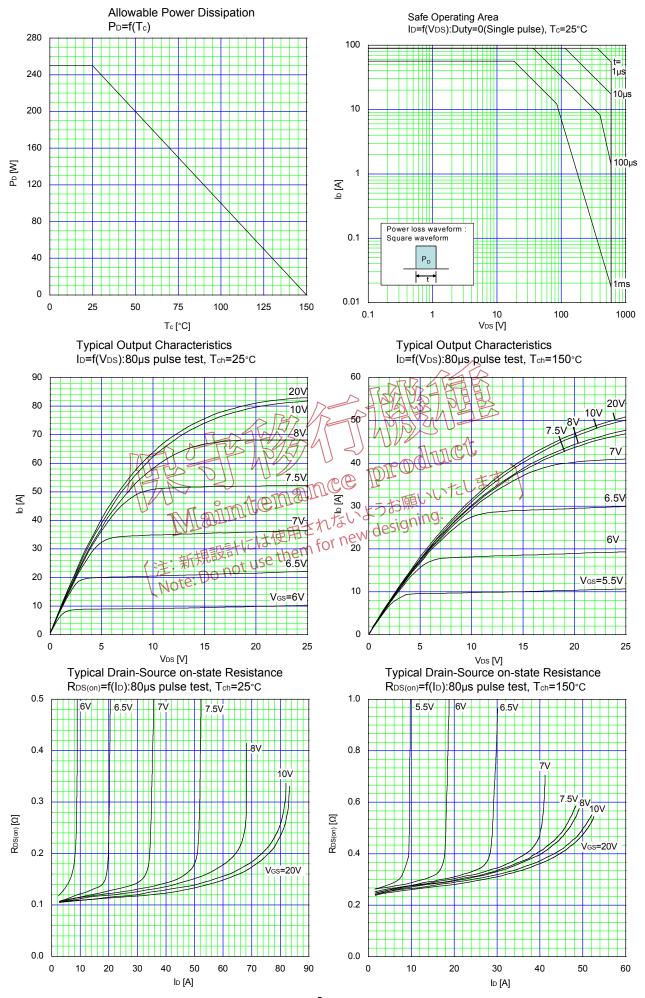
Note *6 : $C_{o(er)}$ is a fixed capacitance that gives the same stored energy as C_{oss} while V_{DS} is rising from 0 to 400V. Note *7 : $C_{o(tr)}$ is a fixed capacitance that gives the same charging times as C_{oss} while V_{DS} is rising from 0 to 400V.

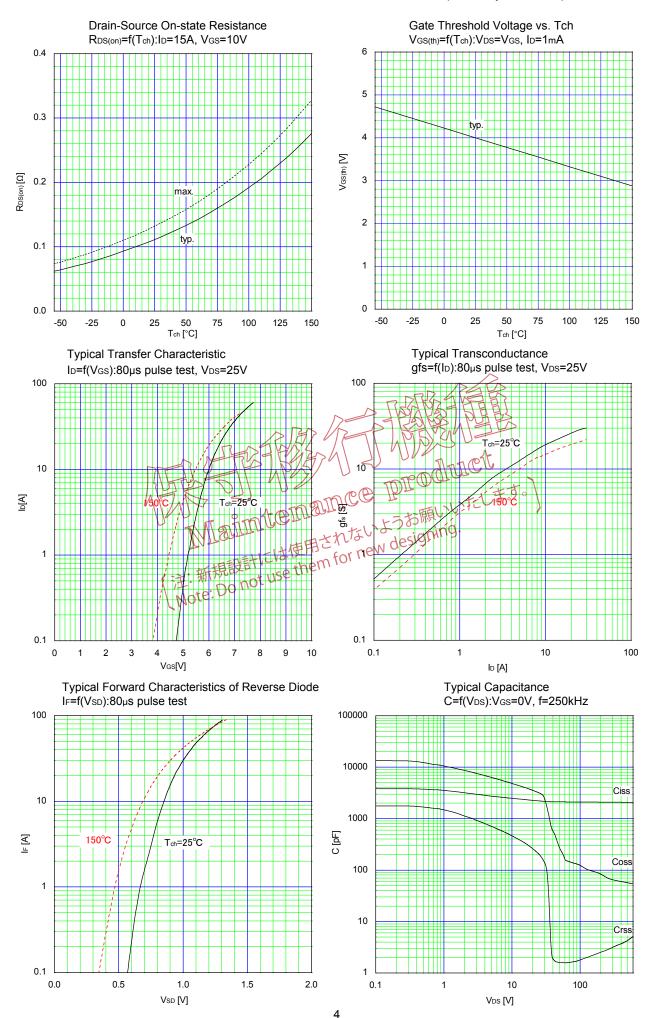
Reverse Diode

Parameter	Symbol	Conditions	s min ge	typ.	max.	Unit
Avalanche Capability	lav R	L=217mH, Tot=25°C See Fig. 7 and Fig. 2	6.6	-	-	A
Diode Forward On-Voltage	THE S	It=30A,Ves=0V Thn=25°C	TUICO	す.)	1.35	V
Reverse Recovery Time		II = 25°C = 21 II = 30A, V _{DD} =400V -di/dt=100A/μg = thts Top=25°C = 4 See Fig.6 and Fig.7 for new design not USE	NTELO	180	-	ns
Reverse Recovery Charge	Q. MISI	Tet=25(g)使用されない。 Tet=25(g)使用されない。 Tet=25(g)使用になってNew design	-	1.2	-	μC
Peak Reverse Recovery Current 🧹	泄:新規副	The Hig S and Fig 7.01	-	13.5	-	А

Thermal Resistance

Parameter	Symbol	min.	typ.	max.	Unit
Channel to Case	Rth(ch-c)	-	-	0.5	°C/W
Channel to Ambient	Rth(ch-a)	-	-	62	°C/W





10⁻²

10⁻³

10⁻⁵

10⁻⁴

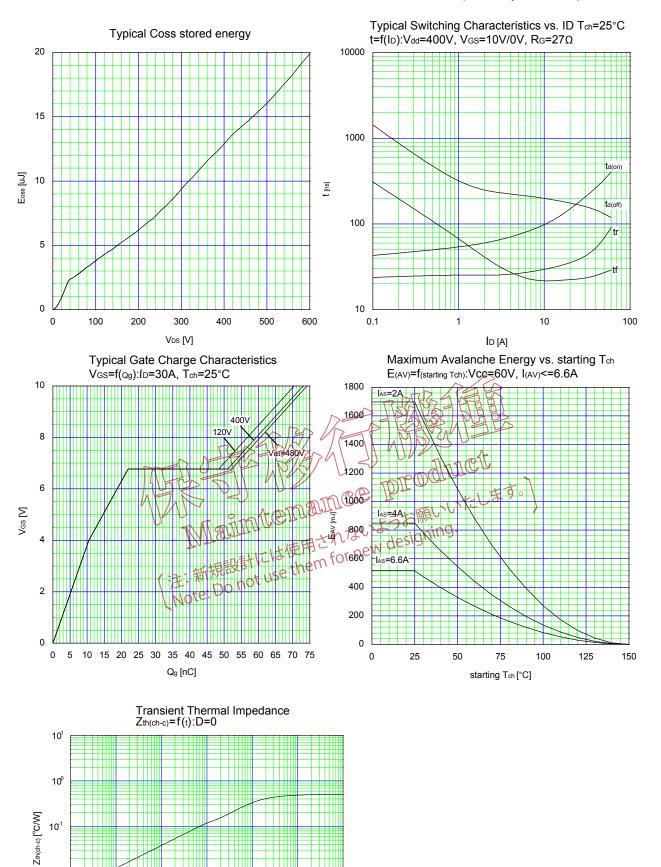
10⁻³

t [sec]

10⁻²

10⁻¹

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10⁰

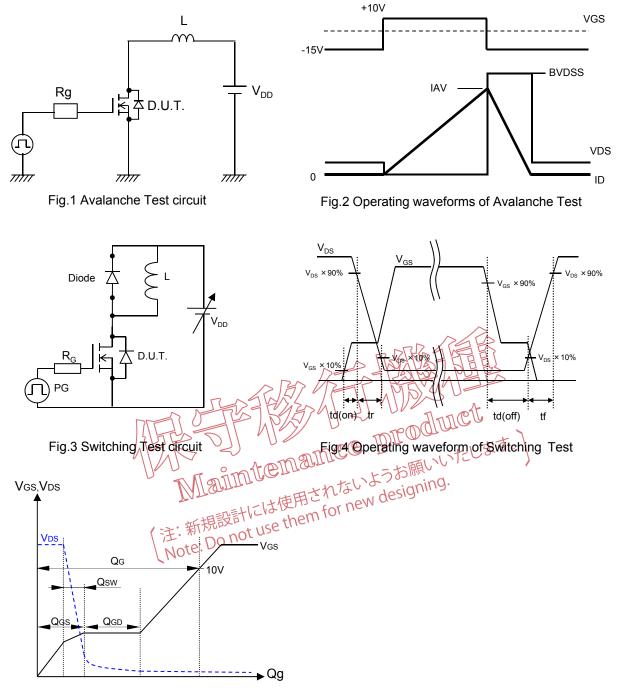
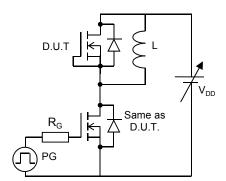


Fig.5 Operating waveform of Gate charge Test



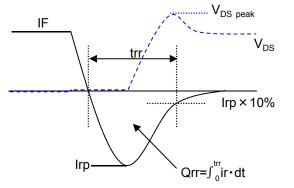
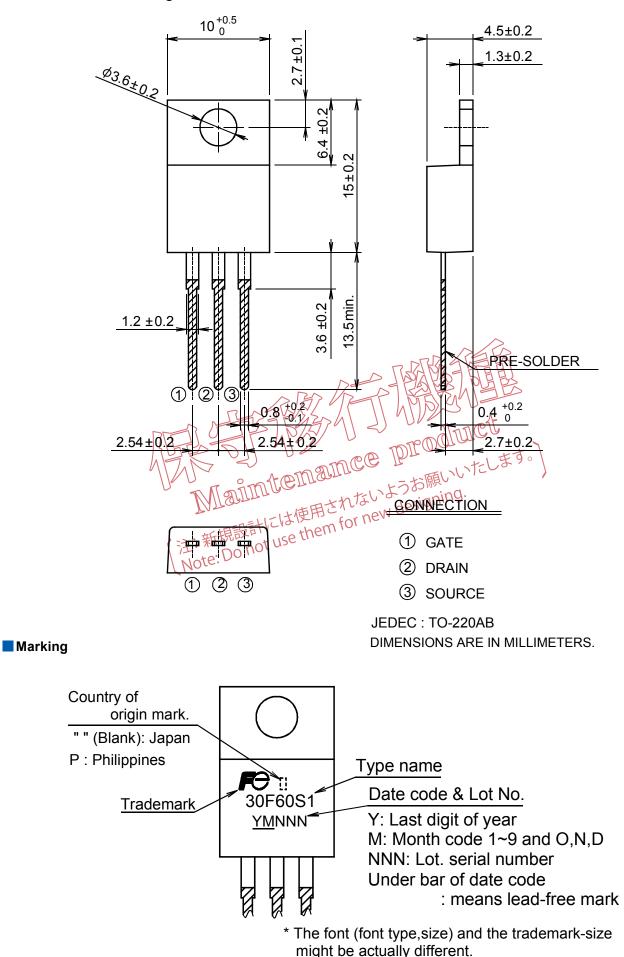


Fig.6 Reverse recovery Test circuit

Fig.7 Operating waveform of Reverse recovery Test

Outview: TO-220 Package



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